





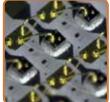
FLIP CHIP SMT PRODUCTION

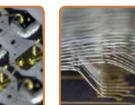
PROTOTYPING W

CHIP ON BOARD

SUPPLY CHAIN MANAGEMENT

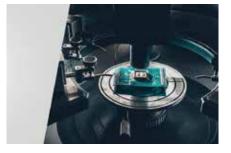














Contact information

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Company

AEMtec is one of the global acting specialists for the development and production of a variety of precision optoelectronic products. With a wide technology portfolio including Wafer Back-End Services, Chip on Board, Flip Chip, 3D Integration and Opto Packaging is AEMtec the right partner for complex and reliable solutions in the sector of miniaturization. The motivation is not only to drive innovations but also to accompany the customer along the entire value chain.

Main products and services

AEMtec GmbH is a full-service provider for miniaturized micro- and optoelectronic modules and even complete systems. The range of services includes design, development, industrialization, qualification, prototyping (NPI), test and test system development, series production, supply chain management and after sales services

The following technologies fulfill customized requirements:

- Wafer Back-End Service (UBM + SBA)
- Chip on Board (Thin Wire Technology)
- Flip Chip (Soldering, Glueing)
- High Precision Placement of Optical Components
- SMT
- System Integration
- Test (ICT, FCT, LTT)

Products for the UK Market

We are a pure contract manufacturer for (opto)-electronic components and systems. Our customers benefit from our broad technology portfolio, a highly experienced engineering team, many years of experience in the field of microelectronics for different markets and applications. We are also ISO9001 (quality management), ISO13485 (medical) and ISO14001 (environment) certified.

Target clients

Our general markets are: medical technology, industry&automation, semiconductors, automotive&transport, aviation&aerospace. Here we are seeking for end customers who in turn are looking for a supplier for miniaturized electronics, opto- electronic packages/systems and high-density hybrids. As we are specialized in high-end applications we are mainly focused on low to medium production volumes up to several 100k pieces per year.

